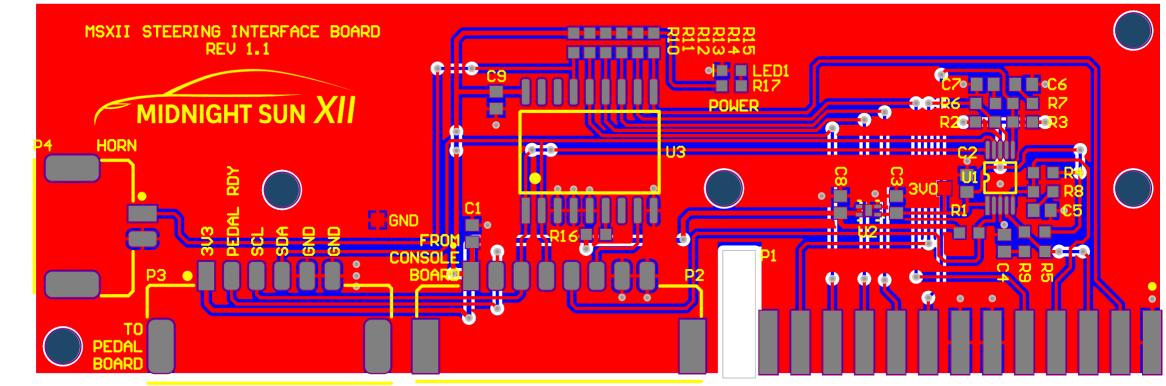
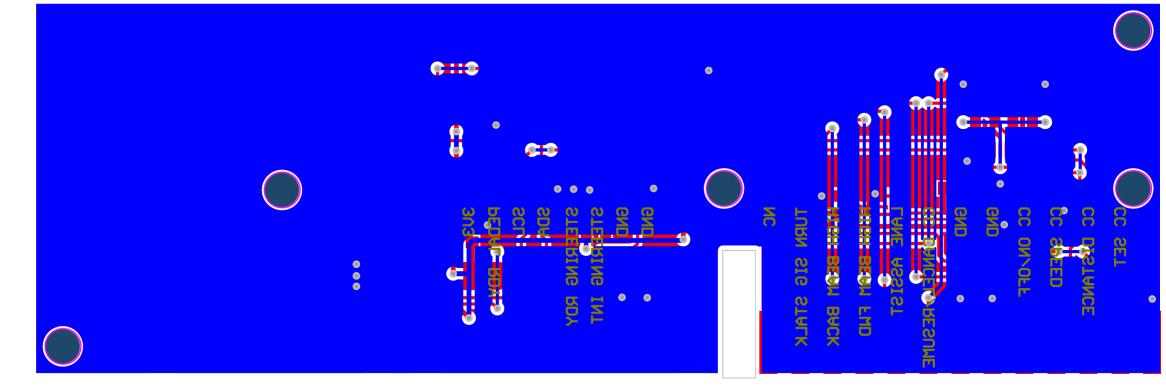


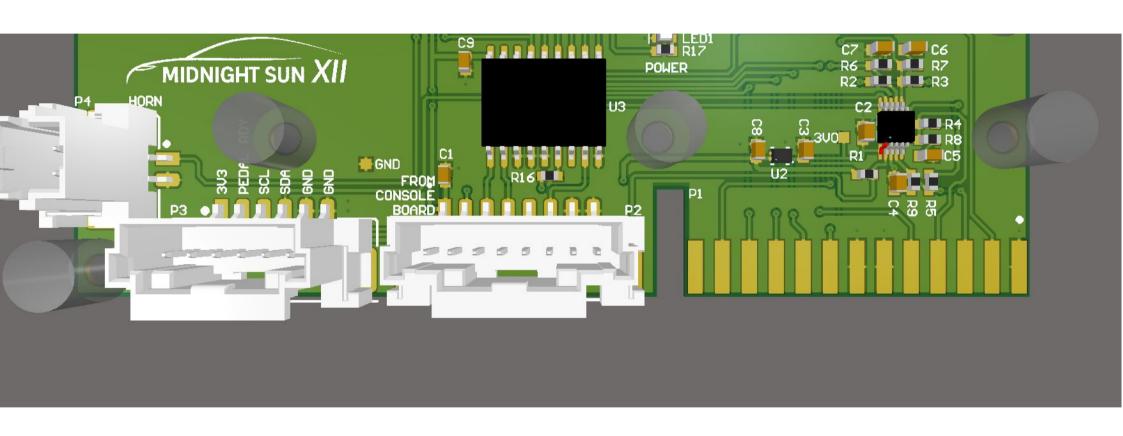
Bill of M	aterials
Project:	XII_SteeringWheelInterfaceBoard.PrjPcb
Revision:	1.1
Project Lead:	Taiping Li
Generated On:	5/20/2018 11:34:29 PM
Production Quantity:	1
Currency	CAD
Total Parts Count:	33



LibRef	Designator	Manufacturer 1	Manufacturer Part Number 1	Supplier 1	Supplier Part Number 1	Supplier Unit Price 1	Supplier Order Qty 1	Supplier Subtotal 1
CAP CER 4.7UF 25V 10% X5R 0603	C1	Murata	GRM188R61E475KE11D	Digi-Key	490-7203-1-ND	0.53	1	\$ 0.53
CAP CER 0.1UF 50V 10% X7R 0603	C2	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	\$ 0.21
CAP CER 1UF 50V 10% X7R 0603	C3	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.37	1	\$ 0.37
CAP CER 1UF 50V 10% X7R 0603	C4	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.37	1	\$ 0.37
CAP CER 1UF 50V 10% X7R 0603	C5	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.37	1	\$ 0.37
CAP CER 1UF 50V 10% X7R 0603	C6	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.37	1	\$ 0.37
CAP CER 1UF 50V 10% X7R 0603	C7	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.37	1	\$ 0.37
CAP CER 1UF 50V 10% X7R 0603	C8	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.37	1	\$ 0.37
CAP CER 0.1UF 50V 10% X7R 0603	C9	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	\$ 0.21
LED GREEN CLEAR 2V 0603	LED1	Wurth Electronics	150060VS75000	Digi-Key	732-4980-1-ND	0.18	1	\$ 0.18
CONN 8POS DURA-CLIK 0.079"	P2	Molex	560020-0820	Digi-Key	WM10868CT-ND	1.85	1	\$ 1.85
CONN 6POS DURA-CLIK 0.079"	P3	<u>Molex</u>	560020-0620	Digi-Key	WM10866CT-ND	1.56	1	\$ 1.56
CONN 2POS DURA-CLIK 0.079" VERT	P4	Molex	560020-0220	Digi-Key	WM10862CT-ND	1.06	1	\$ 1.06
RES 10K OHM 1% 1/10W 0603	R1	Yageo	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$ 0.13
RES 3.83K OHM 1% 1/10W 0603	R2	<u>Yageo</u>	RC0603FR-073K83L	Digi-Key	311-3.83KHRCT-ND	0.13	1	\$ 0.13
RES 3.83K OHM 1% 1/10W 0603	R3	Yageo	RC0603FR-073K83L	Digi-Key	311-3.83KHRCT-ND	0.13	1	\$ 0.13
RES 3.83K OHM 1% 1/10W 0603	R4	Yageo	RC0603FR-073K83L	Digi-Key	311-3.83KHRCT-ND	0.13	1	\$ 0.13
RES 3.83K OHM 1% 1/10W 0603	R5	Yageo	RC0603FR-073K83L	Digi-Key	311-3.83KHRCT-ND	0.13	1	\$ 0.13
RES 100 OHM 1% 1/10W 0603	R6	<u>Yageo</u>	RC0603FR-07100RL	Digi-Key	311-100HRCT-ND	0.13	1	\$ 0.13
RES 100 OHM 1% 1/10W 0603	R7	Yageo	RC0603FR-07100RL	Digi-Key	311-100HRCT-ND	0.13	1	\$ 0.13
RES 100 OHM 1% 1/10W 0603	R8	Yageo	RC0603FR-07100RL	Digi-Key	311-100HRCT-ND	0.13	1	\$ 0.13
RES 100 OHM 1% 1/10W 0603	R9	Yageo	RC0603FR-07100RL	Digi-Key	311-100HRCT-ND	0.13	1	\$ 0.13
RES 10K OHM 1% 1/10W 0603	R10	<u>Yageo</u>	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$ 0.13
RES 10K OHM 1% 1/10W 0603	R11	Yageo	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$ 0.13
RES 10K OHM 1% 1/10W 0603	R12	Yageo	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$ 0.13
RES 10K OHM 1% 1/10W 0603	R13	Yageo	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$ 0.13
RES 10K OHM 1% 1/10W 0603	R14	<u>Yageo</u>	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$ 0.13
RES 10K OHM 1% 1/10W 0603	R15	Yageo	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$ 0.13
RES 10K OHM 1% 1/10W 0603	R16	Yageo	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$ 0.13
RES 604 OHM 1% 1/10W 0603	R17	<u>Yageo</u>	RC0603FR-07604RL	Digi-Key	311-604HRCT-ND	0.13	1	\$ 0.13
IC ADC 12-BIT VSSOP-10	U1	Texas Instruments	ADS1015IDGSR	Digi-Key	296-41185-1-ND	3.55	1	\$ 3.55
IC REG LDO 3V 0.2A 4-TDFN	U2	Microchip	MIC94310-PYMT-TR	Digi-Key	576-4761-1-ND	0.37	1	\$ 0.37
IC I/O EXPANDER I2C 8B 18SOIC	U3	Microchip	MCP23008T-E/SO	Digi-Key	MCP23008T-E/SOCT- ND	1.35	1	\$ 1.35
							Total:	\$ 15.30







Electrical Rules Check Report

Class	Document	Message
Warning	Steering Wheel Interface. SchDoc	Net NetR16_2 has no driving source (Pin R16-2,Pin U3-6)

Design Rules Verification ReportFilename : C:\Users\Taiping\Documents\MidnightSun\hardware\MSXII_SteeringWheelInterfa

Warnings 0 Rule Violations 59

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.254mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.254mm) (Max=0.508mm) (Preferred=0.254mm) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	5
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	18
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	27
Silk to Silk (Clearance=0.254mm) (All),(All)	9
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	59

Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(19.9mm,14.88mm) on Multi-Layer Actual Hole Size = 2.7mm
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(2.5mm, 2.5mm) on Multi-Layer Actual Hole Size = 2.7mm
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(55.002mm,15mm) on Multi-Layer Actual Hole Size = 2.7mm
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(87.5mm,15mm) on Multi-Layer Actual Hole Size = 2.7mm
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(87.5mm,27.5mm) on Multi-Layer Actual Hole Size = 2.7mm

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.188mm < 0.254mm) Between Pad LED1-1(56.342mm,24.339mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.188mm < 0.254mm) Between Pad LED1-2(54.842mm,24.339mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R10-1(43.06mm,27.3mm) on Top Layer And Pad R11-1(44.33mm,27.3mm)
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R10-2(43.06mm,25.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R11-1(44.33mm,27.3mm) on Top Layer And Pad R12-1(45.6mm,27.3mm) on
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R11-2(44.33mm,25.75mm) on Top Layer And Pad R12-2(45.6mm,25.75mm)
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R12-1(45.6mm,27.3mm) on Top Layer And Pad R13-1(46.87mm,27.3mm) on
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R12-2(45.6mm,25.75mm) on Top Layer And Pad R13-2(46.87mm,25.75mm)
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R13-1(46.87mm,27.3mm) on Top Layer And Pad R14-1(48.14mm,27.3mm)
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R13-2(46.87mm,25.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R14-1(48.14mm,27.3mm) on Top Layer And Pad R15-1(49.41mm,27.3mm)
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R14-2(48.14mm,25.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U2-1(67.178mm,12.95mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.012mm < 0.254mm) Between Pad U2-1(67.178mm,12.95mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.012mm < 0.254mm) Between Pad U2-2(67.178mm,13.55mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U2-3(65.738mm,13.55mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-3(65.738mm,13.55mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-4(65.738mm,12.95mm) on Top Layer And Pad

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Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.188mm < 0.254mm) Between Arc (67.686mm, 12.696mm) on Top Overlay And Pad
Silk To Solder Mask Clearance Constraint: (0.042mm < 0.254mm) Between Pad 3V0-TP(72.5mm,15mm) on Top Layer And Text "3V0"
Silk To Solder Mask Clearance Constraint: (0.246mm < 0.254mm) Between Pad C2-1(74.3mm,14.729mm) on Top Layer And Text "U1" (74mm,15.5mm) on
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Pad C2-2(74.3mm, 16.079mm) on Top Layer And Text "U1" (74mm, 15.5mm) on
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED1-2(54.842mm,24.339mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.153mm < 0.254mm) Between Pad P2-(31.3mm,2.5mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.153mm < 0.254mm) Between Pad P2-(52.5mm,2.5mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.18mm < 0.254mm) Between Pad P4-3(3.25mm, 16.605mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.241mm < 0.254mm) Between Pad P4-3(3.25mm, 7.405mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.193mm < 0.254mm) Between Pad U1-1(75.93mm,13.65mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad U1-1(75.93mm,13.65mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.243mm < 0.254mm) Between Pad U1-10(75.93mm,18.05mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.195mm < 0.254mm) Between Pad U1-10(75.93mm,18.05mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.206mm < 0.254mm) Between Pad U1-2(76.43mm,13.65mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.206mm < 0.254mm) Between Pad U1-3(76.93mm,13.65mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.206mm < 0.254mm) Between Pad U1-4(77.43mm,13.65mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.206mm < 0.254mm) Between Pad U1-5(77.93mm,13.65mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U1-5(77.93mm, 13.65mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.195mm < 0.254mm) Between Pad U1-6(77.93mm,18.05mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U1-6(77.93mm, 18.05mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.195mm < 0.254mm) Between Pad U1-7(77.43mm,18.05mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.195mm < 0.254mm) Between Pad U1-8(76.93mm,18.05mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.195mm < 0.254mm) Between Pad U1-9(76.43mm,18.05mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U2-1(67.178mm,12.95mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U2-2(67.178mm,13.55mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U2-3(65.738mm,13.55mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U2-4(65.738mm,12.95mm) on Top Layer And Track

Silk to Silk (Clearance=0.254mm) (AII),(AII)
Silk To Silk Clearance Constraint: (Collision < 0.254mm) Between Arc (33.5mm,10.48mm) on Top Overlay And Text "FROM

CONSOLE

BOARD" (28.4mm,7.6mm) on Top Overlay Silk Text to Silk Clearance [0mm]

Silk to Silk (Clearance=0.254mm) (AII),(AII)
Silk To Silk Clearance Constraint: (0.235mm < 0.254mm) Between Text "LED1" (57.4mm,23.935mm) on Top Overlay And Text "R17" (57.4mm,22.75mm)
Silk To Silk Clearance Constraint: (0.244mm < 0.254mm) Between Text "P3" (9.25mm,7.75mm) on Top Overlay And Track
Silk To Silk Clearance Constraint: (0.218mm < 0.254mm) Between Text "P3" (9.25mm, 7.75mm) on Top Overlay And Track
Silk To Silk Clearance Constraint: (0.25mm < 0.254mm) Between Text "R10" (50.576mm,27.677mm) on Top Overlay And Text "R11"
Silk To Silk Clearance Constraint: (0.25mm < 0.254mm) Between Text "R11" (51.776mm,27.677mm) on Top Overlay And Text "R12"
Silk To Silk Clearance Constraint: (0.25mm < 0.254mm) Between Text "R12" (52.976mm,27.677mm) on Top Overlay And Text "R13"
Silk To Silk Clearance Constraint: (0.25mm < 0.254mm) Between Text "R13" (54.176mm,27.677mm) on Top Overlay And Text "R14"
Silk To Silk Clearance Constraint: (0.25mm < 0.254mm) Between Text "R14" (55.376mm,27.677mm) on Top Overlay And Text "R15"

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